



Product Change Notification / JAON-08IMNP537

Date:

14-Dec-2020

Product Category:

Memory

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4404 Initial Notice: Qualification of ASSH as a new assembly site for 24LC512, 24AA512 and 24FC512 device families available in 8L TSSOP package.

Affected CPNs:

[JAON-08IMNP537_Affected_CPN_12142020.pdf](#)

[JAON-08IMNP537_Affected_CPN_12142020.csv](#)

Notification Text:

PCN Status: Initial notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of ASSH as a new assembly site for 24LC512, 24AA512 and 24FC512 device families available in 8L TSSOP package.

Pre Change:

Assembled at ANAP using gold (Au) bond wire, 8290 die attach, G700A mold compound and C7025 lead frame material with Matte Tin (Sn) plating and Ag Spot DAP Surface Prep plating or Assembled at MMT using gold (Au) bond wire, 2200D die attach, G600V mold compound and C7025 lead frame material with Matte Tin (Sn) plating and Ag Spot DAP Surface Prep plating or Assembled at NSEB using gold (Au) bond wire, 2200D die attach, G600 mold compound and C7025 lead frame material with Matte Tin (Sn) plating and Ag Spot DAP Surface Prep plating.

Method to Identify Change: Traceability code

Qualification Plan Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:December 14, 2020: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_JAON-08IMNP537_Qual_Plan.pdf](#)

[PCN_JAON-08IMNP537_Pre and Post Change_Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

24LC512-I/ST

24AA512-I/ST

24FC512-I/ST

24LC512T-I/ST

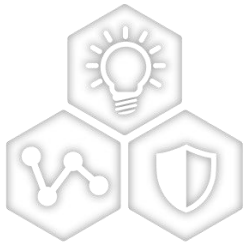
24AA512T-I/ST

24FC512T-I/ST

CCB 4404
Pre and Post Change Summary
PCN #: JAON-08IMNP537

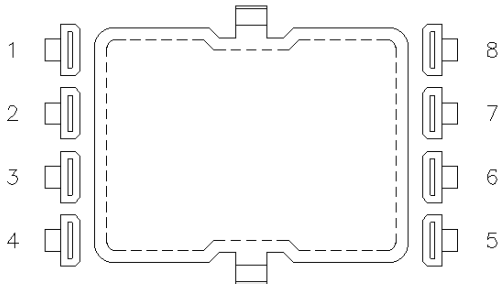
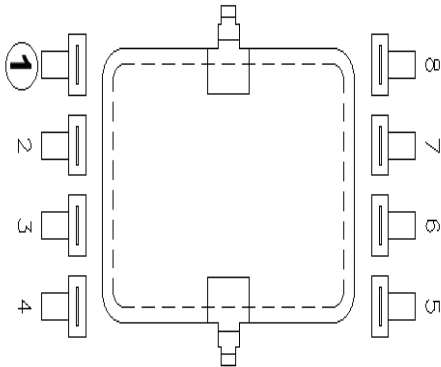
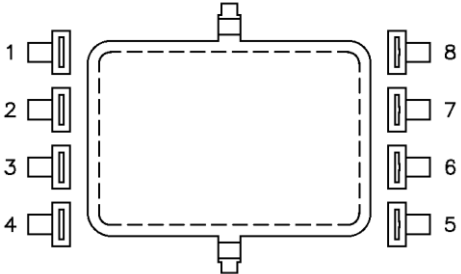
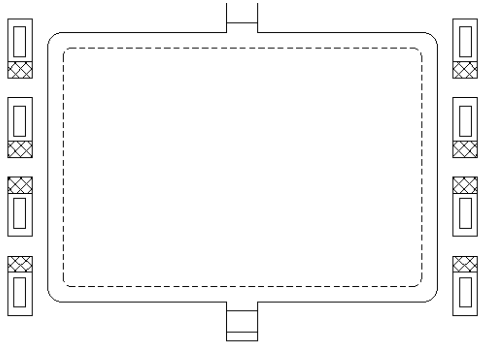


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Lead frame Comparison

Pre Change		Post Change																	
ANAP	MMT	NSEB	ASSH																
																			
<table border="1"> <thead> <tr> <th>DAP Surface Prep</th> <th>Ag Spot</th> </tr> </thead> <tbody> <tr> <td>Lead-Lock</td> <td>No</td> </tr> </tbody> </table>	DAP Surface Prep	Ag Spot	Lead-Lock	No	<table border="1"> <thead> <tr> <th>DAP Surface Prep</th> <th>Ag Spot</th> </tr> </thead> <tbody> <tr> <td>Lead-Lock</td> <td>No</td> </tr> </tbody> </table>	DAP Surface Prep	Ag Spot	Lead-Lock	No	<table border="1"> <thead> <tr> <th>DAP Surface Prep</th> <th>Ag Spot</th> </tr> </thead> <tbody> <tr> <td>Lead-Lock</td> <td>No</td> </tr> </tbody> </table>	DAP Surface Prep	Ag Spot	Lead-Lock	No	<table border="1"> <thead> <tr> <th>DAP Surface Prep</th> <th>Ru-PPF</th> </tr> </thead> <tbody> <tr> <td>Lead-Lock</td> <td>Yes</td> </tr> </tbody> </table>	DAP Surface Prep	Ru-PPF	Lead-Lock	Yes
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Lead-Lock	Yes																		



MICROCHIP

QUALIFICATION PLAN SUMMARY

PCN #: JAON-08IMNP537

Date

October 09, 2020

Qualification of ASSH as a new assembly site for 24LC512, 24AA512 and 24FC512 device families available in 8L TSSOP package.

Purpose: Qualification of ASSH as a new assembly site for 24LC512, 24AA512 and 24FC512 device families available in 8L TSSOP package.

CCB No.: 4404

Package:

Type _____ 8L TSSOP

Width or Size _____ 4.4 mm

Leadframe:

Material _____ C7025

Surface treatment _____ Roughening

Paddle size _____ 126 x 87 mils

Process _____ Stamped

Solder Plating:

Material _____ NiPdAu

Wire:

Material _____ PdCu

Die Attach Film:

Part Number _____ EN-4900G

Conductive _____ Yes

Mold Compound:

Type _____ G700LY

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instructions
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0 fails after TC	5	30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5		5	30 bonds from a min. 5 devices.
Preconditioning - Required for surface mount devices	+150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020D for package type. MSL-1 @ 260°C	231	15	3	738	0	15	Spares should be properly identified. 77 parts from each lot to be used for HAST, Autoclave, Temp Cycle test.
HAST	+130°C/85% RH for 96 hours or 110°C/85%RH for 264 hours. Electrical test pre and post stress at +25°C and hot temp.	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Unbiased HAST	+130°C/85% RH for 96 hrs or +110°C/85% RH for 264 hrs. Electrical test pre and post stress at +25°C	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	-65°C to +150°C for 500 cycles. Electrical test pre and post stress at hot temp; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress.	77	5	3	246	0	15	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.